


GFO-3301 - 1.5~5.5V 32.768kHz Oscillator					
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Au Wire	Metal	Au	7440-57-5	0.026	100.00
	Metal	Pd	7440-53-3	0.000	0.00
Base	Ceramic	Al2O3	1344-28-1	15.929	75.49
	Ceramic	SiO2	14808-60-7	0.778	3.69
	Ceramic	CaO	1305-78-8	0.114	0.54
	Ceramic	MgO	1309-48-4	0.105	0.50
	Ceramic	Cr2O3	1308-38-9	0.121	0.57
	Ceramic	Mo	7439-98-7	0.243	1.15
	Ceramic	W	7440-33-7	2.561	12.14
	Ceramic	Ni	7440-02-0	0.909	4.31
	Ceramic	Co	7440-48-4	0.227	1.08
	Ceramic	Au	7440-57-5	0.114	0.54
	Blank(TUNING FORK)	Quartz(TUNING FORK)	SiO2	14808-60-7	0.400
DIE ADHESIVE	Epoxy resin	Ag	7440-22-4	0.079	71.82
	Epoxy resin	Modified Epoxy Resin	9003-36-5	0.010	9.09
	Epoxy resin	Epoxy resin F type	28064-14-4	0.010	9.09
	Epoxy resin	Epoxy resin A type	25068-38-6	0.009	8.18
	Epoxy resin	Imidazole	827-43-0	0.001	0.91
	Epoxy resin	Amide	461-58-5	0.001	0.91
Electrode	Metal	Au	7440-57-5	0.005	83.33
	Metal	Cr	7440-47-3	0.001	16.67
IC DIE	IC DIE	Si	7440-21-3	0.497	99.40
	IC DIE	Al	7429-90-5	0.003	0.60
	IC DIE	P	7723-14-0	0.000	0.00
	IC DIE	B	7440-42-8	0.000	0.00
	IC DIE	As	7440-38-2	0.000	0.00
	IC DIE	Ti	7440-32-6	0.000	0.00
	IC DIE	W	7440-33-7	0.000	0.00
	IC DIE	Cu	7440-50-8	0.000	0.00
Lid	Direct	Fe	7439-89-6	0.905	20.01
	Direct	Ni	7440-02-0	1.238	27.37
	Direct	Co	7440-48-4	0.384	8.49
	Direct	Mn	7439-96-5	0.005	0.11
	Direct	Si	7440-21-3	0.001	0.02
	Direct	Ag	7440-22-4	0.531	11.74
	Direct	Cu	7440-50-8	1.459	32.26
Silver Glue	Silicone resin	C12H26	112-40-3	0.002	6.45
	Silicone resin	SiO2	14808-60-7	0.002	6.45
	Silicone resin	Silicones/siloxanes	68037-58-1	0.003	9.68
	Silicone resin	Ag	7440-22-4	0.024	77.42

# Material Composition Data

Product: GFO-3301

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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
				<b>Total Mass:</b>	<b>26.697 mg</b>
					
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